



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: )  
Shinji TAKEDA et al. ) Atty. Docket: TM&K0007  
Serial No. 09/785,436 ) Group Art Unit: 2829  
Filed: February 20, 2001 ) Examiner: GEYER, S.  
For: SEMICONDUCTOR DEVICE AND )  
PROCESS FOR FABRICATION ) Date: June 27, 2002  
THEREOF )

#16/Election  
Amtd  
Amend  
7/8/02

**AMENDMENT (D) AND REQUEST FOR RECONSIDERATION  
OF RESTRICTION/ELECTION REQUIREMENT**

**BOX: NO FEE RESPONSE**  
Assistant Commissioner for Patents  
Washington, D. C. 20231

Sir:

In response to the official Office Action dated June 4, 2002, please amend the above-captioned application, as follows:

**IN THE CLAIMS**

Please add new claims 61 and 62 as follows:

61. (NEW) A semiconductor device comprising a support member, a semiconductor chip, an attaching member for attaching the semiconductor chip to the support member, and an encapsulant resin encapsulating the support member, the semiconductor chip and the attaching member, wherein:

the attaching member is a cured product of a die-bonding material;

the die-bonding material is a film comprising one or more resins selected from the group consisting of silicone resin, acrylic resin, polyimide resin and epoxy resin; and

the film having a peel strength of 0.5 Kg/5 x 5 mm chip or above at a stage where the

RECEIVED  
JUL - 8 2002  
TECHNOLOGY CENTER 2800

DI